

# STS4DPF30L

# DUAL P-CHANNEL 30V - 0.07 $\Omega$ - 4A SO-8 STripFET™ POWER MOSFET

### PRELIMINARY DATA

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STS4DPF30L	30 V	<0.08 Ω	4 A

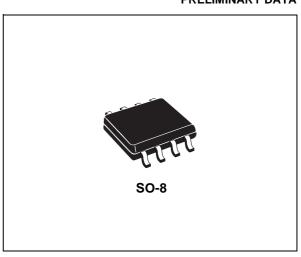
- TYPICAL  $R_{DS}(on) = 0.07 \Omega$
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- LOW THRESHOLD DRIVE

### **DESCRIPTION**

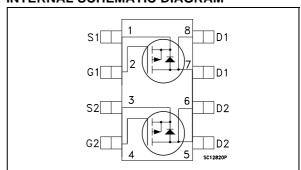
This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low onresistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

### **APPLICATIONS**

- BATTERY MANAGEMENT IN NOMADIC **EQUIPMENT**
- POWER MANAGEMENT IN CELLULAR **PHONES**
- DC-DC CONVERTER



### **INTERNAL SCHEMATIC DIAGRAM**



### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 k $\Omega$ )	30	V
V <sub>GS</sub>	Gate- source Voltage	± 16	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C Single Operation Drain Current (continuous) at T <sub>C</sub> = 100°C Single Operation	4 2.5	A A
I <sub>DM</sub> (●)	Drain Current (pulsed)	16	А
P <sub>tot</sub>	Total Dissipation at $T_C = 25^{\circ}C$ Dual Operation Total Dissipation at $T_C = 25^{\circ}C$ Single Operation	2.0 1.6	W W

(•) Pulse width limited by safe operating area.

Note: For the P-CHANNEL MOSFET actual polarity of voltages and current has to be reversed

This is preliminary information on a new product now in development or undergoing evaluation. Details are subject to change without notice.

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## THERMAL DATA

Rthj-amb (	(*)Thermal Resistance Junction-ambient	Single Operation Dual Operating	78 62.5	°C/W
, ,	Thermal Operating Junction-ambient Storage Temperature	Buai Operating	-55 to 150 -55 to 150	°C

<sup>(\*)</sup> When Mounted on 1 inch<sup>2</sup> FR-4 board, 2 oz of Cu and  $t \le 10$  sec.

# **ELECTRICAL CHARACTERISTICS** (T<sub>CASE</sub> = 25 °C UNLESS OTHERWISE SPECIFIED)

## OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating T_C = 125^{\circ}C$			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 16 V			±100	nA

## ON (\*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I <sub>D</sub> = 250 μA	1			V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V V <sub>GS</sub> = 4.5 V	$I_D = 2 A$ $I_D = 2 A$		0.070 0.085	0.08 0.10	$\Omega$

### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	$V_{DS}$ = 15V $I_D$ = 2 A		10		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$ , f = 1 MHz, $V_{GS} = 0$		1350 490 130		pF pF pF

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# **ELECTRICAL CHARACTERISTICS** (continued)

## SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time	$\begin{aligned} V_{DD} &= 15 \text{ V} & I_D &= 2 \text{ A} \\ R_G &= 4.7 \ \Omega & V_{GS} &= 4.5 \text{ V} \\ \text{(Resistive Load, Figure 1)} \end{aligned}$		25 35		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD}$ = 24 V $I_{D}$ = 4 A $V_{GS}$ = 5 V (See test circuit, Figure 2)		12.5 5 3	16	nC nC nC

### **SWITCHING OFF**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(Off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time	$\begin{split} V_{DD} &= 15 \text{ V} & I_D = 2 \text{ A} \\ R_G &= 4.7 \Omega, & V_{GS} = 4.5 \text{ V} \\ \text{(Resistive Load, Figure 1)} \end{split}$		125 35		ns ns

### SOURCE DRAIN DIODE

Symbol	Symbol Parameter Test Conditions		Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				4 16	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 4 A V <sub>GS</sub> = 0			1.2	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 4 \text{ A}$		45 36 1.6		ns nC A

<sup>(\*)</sup>Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

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Fig. 1: Switching Times Test Circuits For Resistive Load

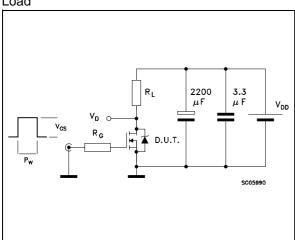


Fig. 2: Gate Charge test Circuit

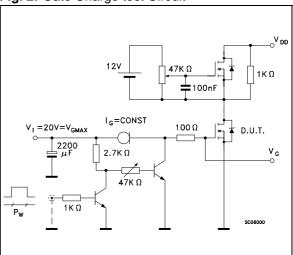
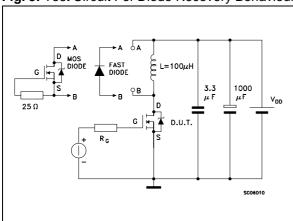


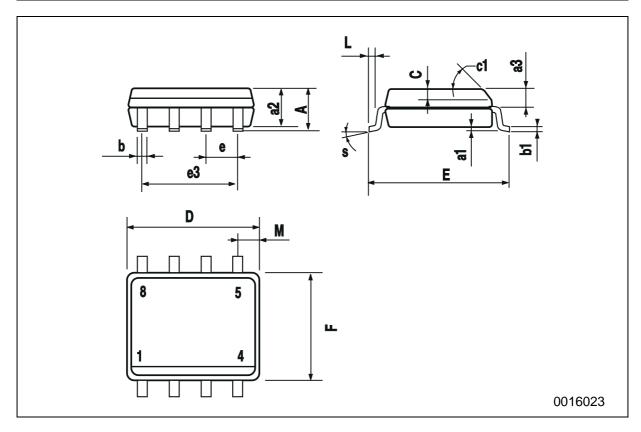
Fig. 3: Test Circuit For Diode Recovery Behaviour



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# **SO-8 MECHANICAL DATA**

DIM.		mm		inch			
DIWI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А			1.75			0.068	
a1	0.1		0.25	0.003		0.009	
a2			1.65			0.064	
a3	0.65		0.85	0.025		0.033	
b	0.35		0.48	0.013		0.018	
b1	0.19		0.25	0.007		0.010	
С	0.25		0.5	0.010		0.019	
c1			45	(typ.)			
D	4.8		5.0	0.188		0.196	
Е	5.8		6.2	0.228		0.244	
е		1.27			0.050		
e3		3.81			0.150		
F	3.8		4.0	0.14		0.157	
L	0.4		1.27	0.015		0.050	
М			0.6			0.023	
S			8 (r	nax.)			



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